TYPICAL CHARACTERISTICS(1)(2)

CHARACTERISTIC DATA (V_I = 5 V)

EFFICIENCY VS LOAD CURRENT

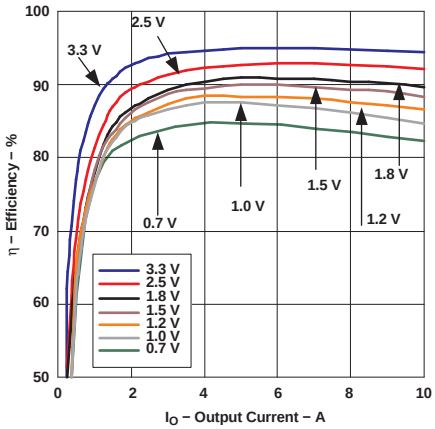

Figure 1.

OUTPUT RIPPLE VS LOAD CURRENT

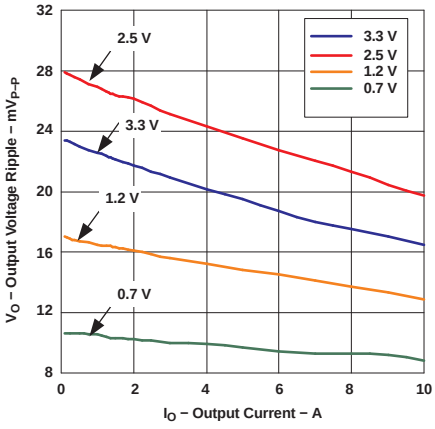

Figure 2.

POWER DISSIPATION VS LOAD CURRENT

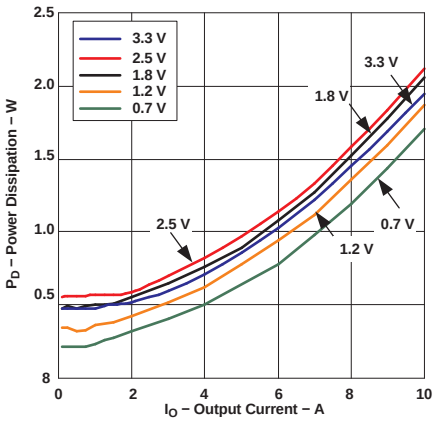

Figure 3.

SAFE OPERATING AREA

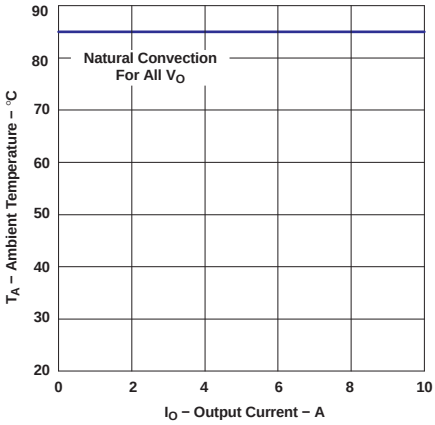

Figure 4.

(1) The electrical characteristic data has been developed from actual products tested at 25C. This data is considered typical for the converter. Applies to Figure 1, Figure 2, and Figure 3.

(2) The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 100 mm x 100 mm double-sided PCB with 2 oz. copper. For surface mount packages (AS and AZ suffix), multiple vias must be utilized. Please refer to the mechanical specification for more information. Applies to Figure 4.

TYPICAL CHARACTERISTICS(1)(2)

CHARACTERISTIC DATA (V_I = 3.3 V)

EFFICIENCY VS LOAD CURRENT

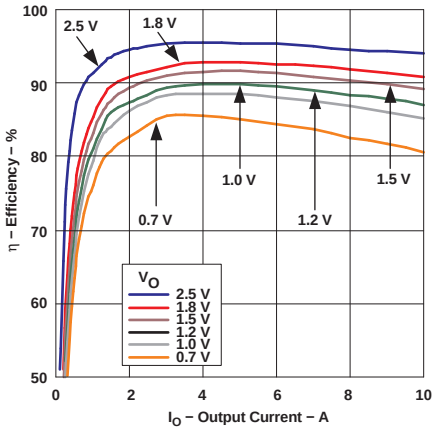

Figure 5.

OUTPUT RIPPLE VS LOAD CURRENT

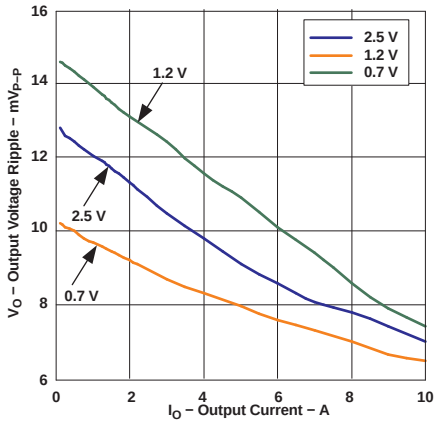

Figure 6.

POWER DISSIPATION VS LOAD CURRENT

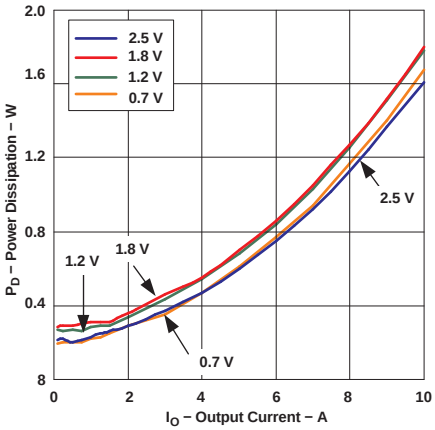

Figure 7.

SAFE OPERATING AREA

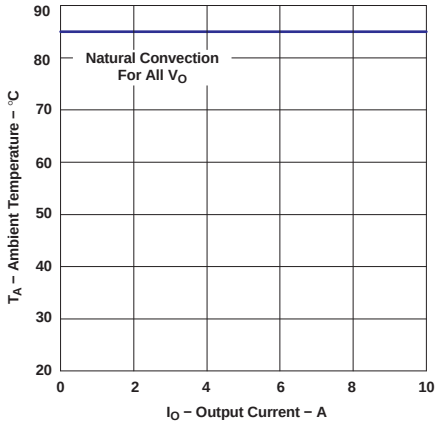

Figure 8.

(1) The electrical characteristic data has been developed from actual products tested at 25C. This data is considered typical for the converter. Applies to Figure 5, Figure 6, and Figure 7.

(2) The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 100 mm x 100 mm double-sided PCB with 2 oz. copper. For surface mount packages (AS and AZ suffix), multiple vias must be utilized. Please refer to the mechanical specification for more information. Applies to Figure 8.